

## **AMENDMENTS TO THE ABSTRACT**

Please cancel the Abstract section of the specification and replace with the following:

A method of distributing power in a semiconductor die comprises providing at least one pair of bond pads to the semiconductor die. An input/output bond pad is provided to an outer periphery of the semiconductor die. The input/output bond pad receives an input/output bond wire operable for electrically connecting to a lead finger of a package. The lead finger is arranged on the package outside of the outer periphery of the semiconductor die. A single corresponding bond wire is connected between each of the pair of bond pads such that each bond pad of each of the pair of bond pads has only one bond wire end connected thereto. A first bond pad of the pair of bond pads is located in an internal portion of the semiconductor die. The input/output bond pad is electrically connected to a second bond pad of the pair of bond pads.